PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
DCV010505DP	ACTIVE	PDIP	NVA	7	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
DCV010505DP-U	ACTIVE	SOP	DUA	7	25	Pb-Free (RoHS)	CU NIPDAU	Level-3-260C-168 HR
DCV010505P	ACTIVE	PDIP	NVA	7	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
DCV010505P-U	ACTIVE	SOP	DUA	7	25	Pb-Free (RoHS)	CU NIPDAU	Level-3-260C-168 HR
DCV010505P-U/700	ACTIVE	SOP	DUA	7	700	Pb-Free (RoHS)	CU NIPDAU	Level-3-260C-168 HR
DCV010505P-U/700E4	ACTIVE	SOP	DUA	7	700	Pb-Free (RoHS)	CU NIPDAU	Level-3-260C-168 HR
DCV010512DP	ACTIVE	PDIP	NVA	7	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
DCV010512DP-U	ACTIVE	SOP	DUA	7	25	Pb-Free (RoHS)	CU NIPDAU	Level-3-260C-168 HR
DCV010512DP-U/700	ACTIVE	SOP	DUA	7	700	Pb-Free (RoHS)	CU NIPDAU	Level-3-260C-168 HR
DCV010512P	ACTIVE	PDIP	NVA	7	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
DCV010512P-U	ACTIVE	SOP	DUA	7	25	Pb-Free (RoHS)	CU NIPDAU	Level-3-260C-168 HR
DCV010515DP	ACTIVE	PDIP	NVA	7	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
DCV010515DP-U	ACTIVE	SOP	DUA	7	25	Pb-Free (RoHS)	CU NIPDAU	Level-3-260C-168 HR
DCV010515P	ACTIVE	PDIP	NVA	7	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
DCV010515P-U	ACTIVE	SOP	DUA	7	25	Pb-Free (RoHS)	CU NIPDAU	Level-3-260C-168 HR
DCV011512DP	ACTIVE	PDIP	NVA	7	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
DCV011512DP-U	ACTIVE	SOP	DUA	7	25	Pb-Free (RoHS)	CU NIPDAU	Level-3-260C-168 HR
DCV011512DP-U/700	ACTIVE	SOP	DUA	7	700	Pb-Free (RoHS)	CU NIPDAU	Level-3-260C-168 HR
DCV011515DP	ACTIVE	PDIP	NVA	7	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
DCV011515DP-U	ACTIVE	SOP	DUA	7	25	Pb-Free (RoHS)	CU NIPDAU	Level-3-260C-168 HR
DCV011515DP-U/700	ACTIVE	SOP	DUA	7	700	Pb-Free (RoHS)	CU NIPDAU	Level-3-260C-168 HR
DCV012405P	ACTIVE	PDIP	NVA	7	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
DCV012405P-U	ACTIVE	SOP	DUA	7	25	Pb-Free (RoHS)	CU NIPDAU	Level-3-260C-168 HR
DCV012405P-U/700	ACTIVE	SOP	DUA	7	700	Pb-Free (RoHS)	CU NIPDAU	Level-3-260C-168 HR
DCV012415DP	ACTIVE	PDIP	NVA	7	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type

Orderable Device	Status [1]	Package Type	Package Drawing	Pins	Package Qty	Eco Plan [2]	Lead/Ball Finish	MSL Peak Temp [3]
DCV012415DP-U	ACTIVE	SOP	DUA	7	25	Pb-Free (RoHS)	CU NIPDAU	Level-3-260C-168 HR
DCV012415DP-U/700	ACTIVE	SOP	DUA	7	700	Pb-Free (RoHS)	CU NIPDAU	Level-3-260C-168 HR

[1] The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

[2] Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

[3] MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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